

**MC14510B**

**BCD Up/Down Counter**

The MC14510B synchronous up/down BCD counter is constructed with MOS P-channel and N-channel enhancement mode devices in a monolithic structure. The counter consists of type D flip-flop stages with a gating structure to provide type T flip-flop capability.

This counter can be preset by applying the desired value in BCD to the Preset inputs (P1, P2, P3, P4) and then bringing the Preset Enable (PE) high. The direction of counting is controlled by applying a high (for up counting) or a low (for down counting) to the UP/DOWN input. The state of the counter changes on the positive transition of the clock input.

Cascading can be accomplished by connecting the Carry Out to the Carry In of the next stage while clocking each counter in parallel. The outputs (Q1, Q2, Q3, Q4) can be reset to a low state by applying a high to the Reset (R) pin.

This CMOS counter finds primary use in up/down and difference counting. Other applications include: (1) Frequency synthesizer applications where low power dissipation and/or high noise immunity is desired, (2) Analog-to-digital and digital-to-analog conversions, and (3) Magnitude and sign generation.

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Internally Synchronous for High Speed
- Logic Edge-Clocked Design — Count Occurs on Positive Going Edge of Clock
- Asynchronous Preset Enable Operation
- Capable of Driving Two Low-power TTL Loads or One Low-power Schottky TTL Load Over the Rated Temperature Range.

**MAXIMUM RATINGS\*** (Voltages Referenced to V<sub>SS</sub>)

Symbol	Parameter	Value	Unit
V <sub>DD</sub>	DC Supply Voltage	- 0.5 to + 18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage (DC or Transient)	- 0.5 to V <sub>DD</sub> + 0.5	V
I <sub>in</sub> , I <sub>out</sub>	Input or Output Current (DC or Transient), per Pin	± 10	mA
P <sub>D</sub>	Power Dissipation, per Package†	500	mW
T <sub>stg</sub>	Storage Temperature	- 65 to + 150	°C
T <sub>L</sub>	Lead Temperature (8-Second Soldering)	260	°C

\* Maximum Ratings are those values beyond which damage to the may occur.

† Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

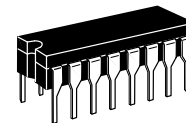
Ceramic "L" Packages: - 12 mW/°C From 100°C To 125°C

**TRUTH TABLE**

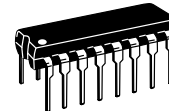
Carry In	Up/Down	Preset Enable	Reset	Clock	Action
1	X	0	0	X	No Count
0	1	0	0	⎯	Count Up
0	0	0	0	⎯	Count Down
X	X	1	0	X	Preset
X	X	X	1	X	Reset

X = Don't Care

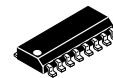
NOTE: When counting up, the Carry Out signal is normally high, and is low only when Q1 and Q4 are high and Carry In is low. When counting down, Carry Out is low only when Q1 through Q4 and Carry In are low.



**L SUFFIX**  
CERAMIC  
CASE 620



**P SUFFIX**  
PLASTIC  
CASE 648



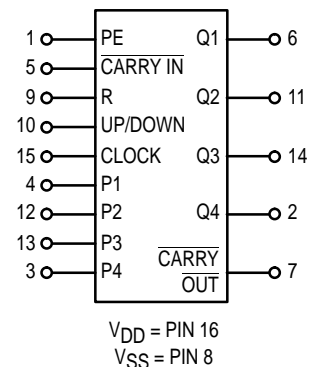
**D SUFFIX**  
SOIC  
CASE 751B

**ORDERING INFORMATION**

MC14XXXBCP Plastic  
MC14XXXBCL Ceramic  
MC14XXXBD SOIC

T<sub>A</sub> = - 55° to 125°C for all packages.

**BLOCK DIAGRAM**



This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V<sub>in</sub> and V<sub>out</sub> should be constrained to the range V<sub>SS</sub> ≤ (V<sub>in</sub> or V<sub>out</sub>) ≤ V<sub>DD</sub>.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V<sub>SS</sub> or V<sub>DD</sub>). Unused outputs must be left open.

**ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

Characteristic	Symbol	V <sub>DD</sub> Vdc	- 55°C		25°C			125°C		Unit	
			Min	Max	Min	Typ #	Max	Min	Max		
Output Voltage V <sub>in</sub> = V <sub>DD</sub> or 0	"0" Level V <sub>OL</sub>	5.0	—	0.05	—	0	0.05	—	0.05	Vdc	
		10	—	0.05	—	0	0.05	—	0.05		
15		—	0.05	—	0	0.05	—	0.05			
V <sub>in</sub> = 0 or V <sub>DD</sub>	"1" Level V <sub>OH</sub>	5.0	4.95	—	4.95	5.0	—	4.95	—	Vdc	
		10	9.95	—	9.95	10	—	9.95	—		
		15	14.95	—	14.95	15	—	14.95	—		
Input Voltage (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)	"0" Level V <sub>IL</sub>	5.0	—	1.5	—	2.25	1.5	—	1.5	Vdc	
		10	—	3.0	—	4.50	3.0	—	3.0		
		15	—	4.0	—	6.75	4.0	—	4.0		
	"1" Level (V <sub>O</sub> = 0.5 or 4.5 Vdc) (V <sub>O</sub> = 1.0 or 9.0 Vdc) (V <sub>O</sub> = 1.5 or 13.5 Vdc)	V <sub>IH</sub>	5.0	3.5	—	3.5	2.75	—	3.5	—	Vdc
			10	7.0	—	7.0	5.50	—	7.0	—	
			15	11	—	11	8.25	—	11	—	
Output Drive Current (V <sub>OH</sub> = 2.5 Vdc) (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)	Source I <sub>OH</sub>	5.0	- 3.0	—	- 2.4	- 4.2	—	- 1.7	—	mAdc	
		5.0	- 0.64	—	- 0.51	- 0.88	—	- 0.36	—		
		10	- 1.6	—	- 1.3	- 2.25	—	- 0.9	—		
		15	- 4.2	—	- 3.4	- 8.8	—	- 2.4	—		
	Sink I <sub>OL</sub>	5.0	0.64	—	0.51	0.88	—	0.36	—	mAdc	
		10	1.6	—	1.3	2.25	—	0.9	—		
15	4.2	—	3.4	8.8	—	2.4	—	—			
Input Current	I <sub>in</sub>	15	—	± 0.1	—	± 0.00001	± 0.1	—	± 1.0	μAdc	
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	—	—	—	—	5.0	7.5	—	—	pF	
Quiescent Current (Per Package)	I <sub>DD</sub>	5.0	—	5.0	—	0.005	5.0	—	150	μAdc	
		10	—	10	—	0.010	10	—	300		
		15	—	20	—	0.015	20	—	600		
Total Supply Current**† (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)	I <sub>T</sub>	5.0	I <sub>T</sub> = (0.58 μA/kHz) f + I <sub>DD</sub> I <sub>T</sub> = (1.20 μA/kHz) f + I <sub>DD</sub> I <sub>T</sub> = (1.70 μA/kHz) f + I <sub>DD</sub>							μAdc	
10											
15											

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

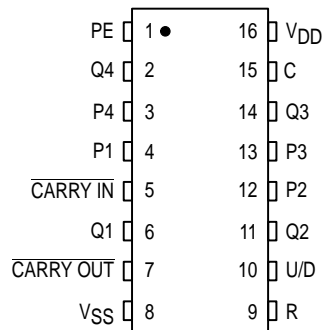
\*\*The formulas given are for the typical characteristics only at 25°C.

†To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) Vfk$$

where: I<sub>T</sub> is in μA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> - V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.001.

**PIN ASSIGNMENT**



**SWITCHING CHARACTERISTICS\*** ( $C_L = 50 \text{ pF}$ ,  $T_A = 25^\circ\text{C}$ , See Figure 2)

Characteristic	Symbol	$V_{DD}$	All Types			Unit
			Min	Typ #	Max	
Output Rise and Fall Time $t_{TLH}$ , $t_{THL} = (1.5 \text{ ns/pF}) C_L + 25 \text{ ns}$ $t_{TLH}$ , $t_{THL} = (0.75 \text{ ns/pF}) C_L + 12.5 \text{ ns}$ $t_{TLH}$ , $t_{THL} = (0.55 \text{ ns/pF}) C_L + 9.5 \text{ ns}$	$t_{TLH}$ , $t_{THL}$	5.0 10 15	— — —	100 50 40	200 100 80	ns
Propagation Delay Time Clock to Q $t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$  Clock to Carry Out $t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$  Carry In to Carry Out $t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 47 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 35 \text{ ns}$  Preset or Reset to Q $t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 230 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 97 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 75 \text{ ns}$  Preset or Reset to Carry Out $t_{PLH}$ , $t_{PHL} = (1.7 \text{ ns/pF}) C_L + 465 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.66 \text{ ns/pF}) C_L + 192 \text{ ns}$ $t_{PLH}$ , $t_{PHL} = (0.5 \text{ ns/pF}) C_L + 125 \text{ ns}$	$t_{PLH}$ , $t_{PHL}$	5.0 10 15	— — —	315 130 100	630 260 200	ns
Reset Pulse Width	$t_{w(H)}$	5.0 10 15	360 210 160	180 105 80	— — —	ns
Clock Pulse Width	$t_{w(H)}$	5.0 10 15	350 170 140	200 100 75	— — —	ns
Clock Pulse Frequency	$f_{cl}$	5.0 10 15	— — —	3.0 6.0 8.0	1.5 3.0 4.0	MHz
Preset or Reset Removal Time The Preset or Reset Signal must be low prior to a positive-going transition of the clock.	$t_{rem}$	5.0 10 15	650 230 180	325 115 90	— — —	ns
Clock Rise and Fall Time	$t_{TLH}$ , $t_{THL}$	5.0 10 15	— — —	— — —	15 5 4	$\mu\text{s}$
Setup Time Carry In to Clock	$t_{su}$	5.0 10 15	260 120 100	130 60 50	— — —	ns
Hold Time Clock to Carry In	$t_h$	5.0 10 15	0 10 10	-50 -15 -5	— — —	ns
Setup Time Up/Down to Clock	$t_{su}$	5.0 10 15	500 200 175	250 100 75	— — —	ns
Hold Time Clock to Up/Down	$t_h$	5.0 10 15	-70 -30 -20	-140 -80 -50	— — —	ns
Setup Time Pn to PE	$t_{su}$	5.0 10 15	-50 -30 -25	-100 -65 -55	— — —	ns
Hold Time PE to Pn	$t_h$	5.0 10 15	480 410 410	240 205 205	— — —	ns
Preset Enable Pulse Width	$t_{WH}$	5.0 10 15	200 100 80	100 50 40	— — —	ns

\* The formulas given are for the typical characteristics only at  $25^\circ\text{C}$ .

#Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

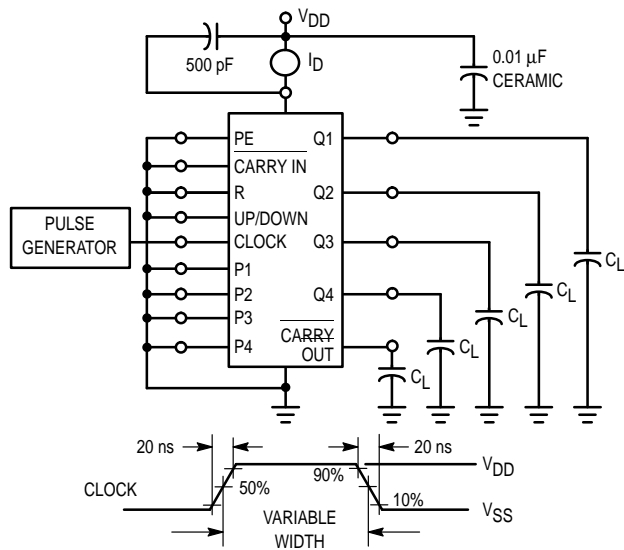


Figure 1. Power Dissipation Test Circuit and Waveform

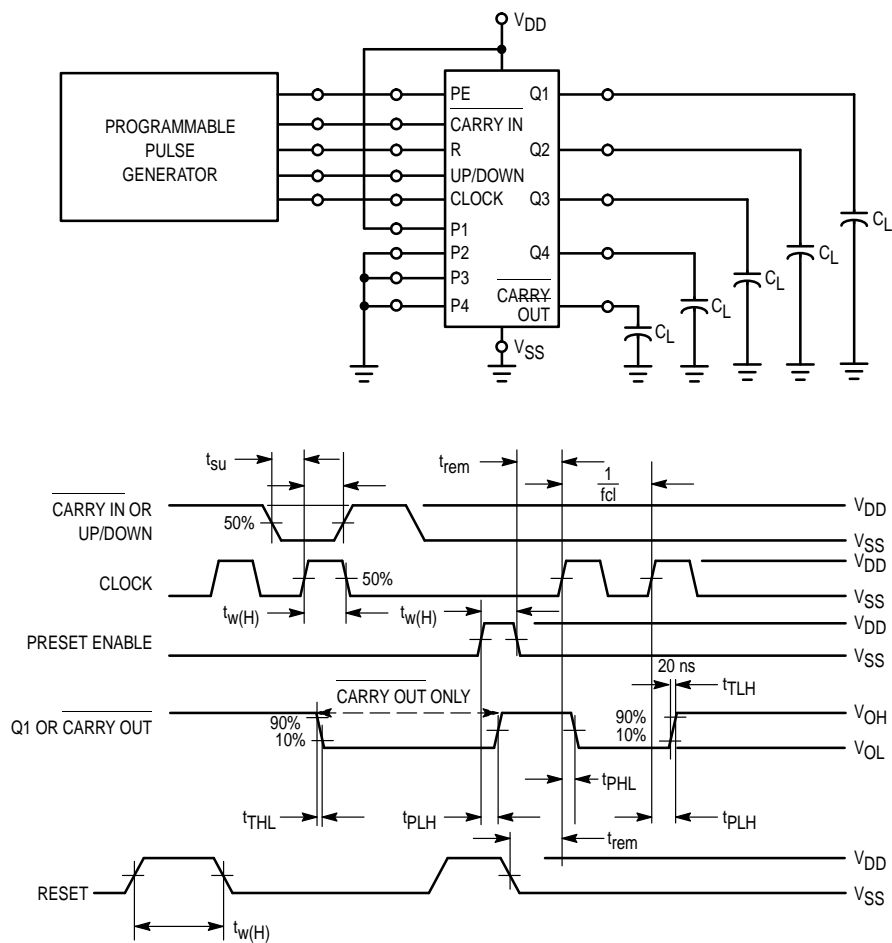
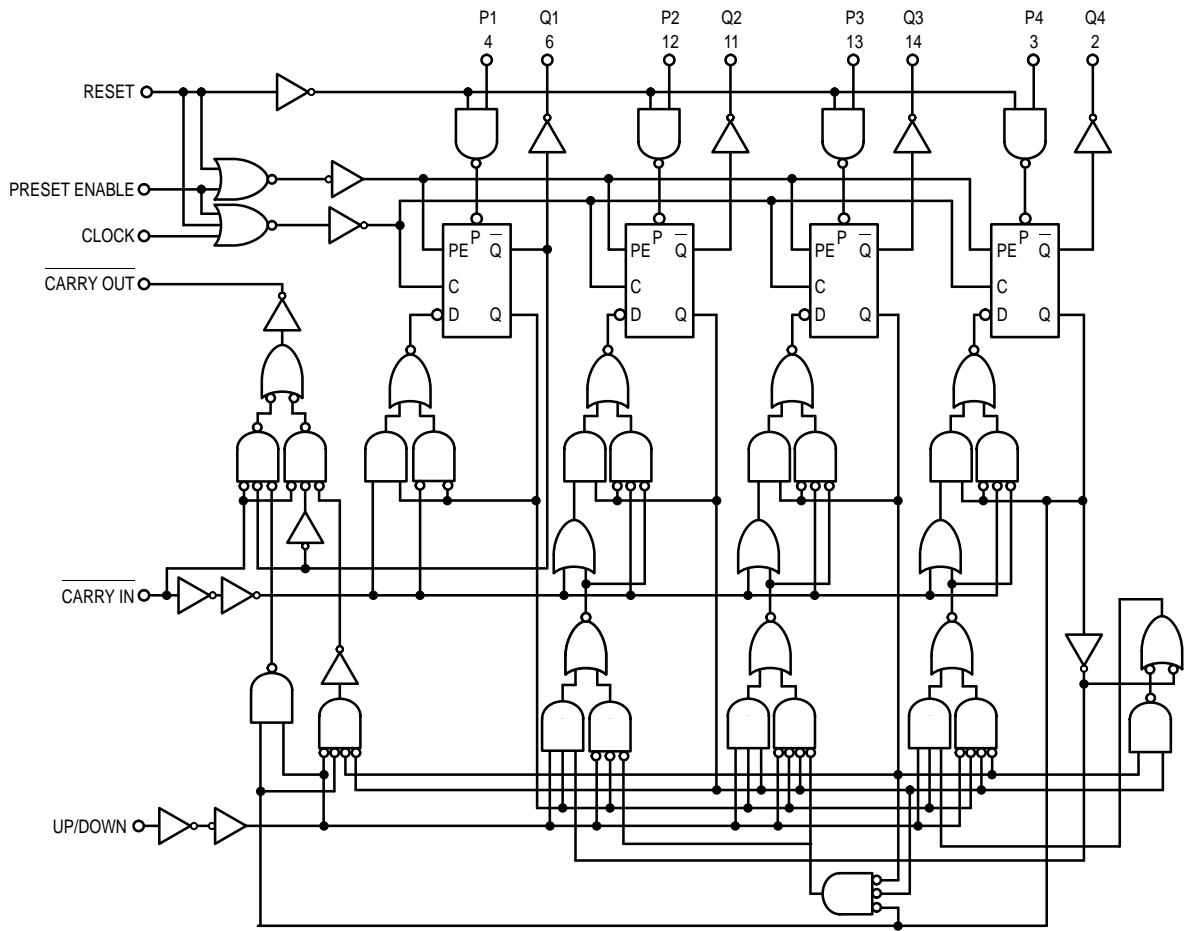
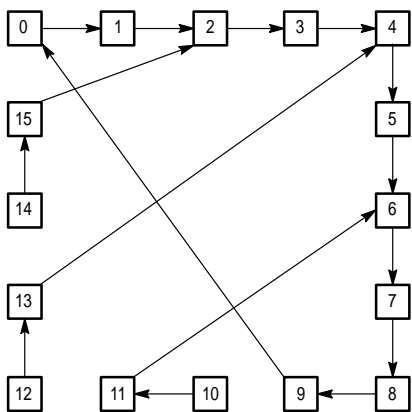


Figure 2. Switching Time Test Circuit and Waveforms

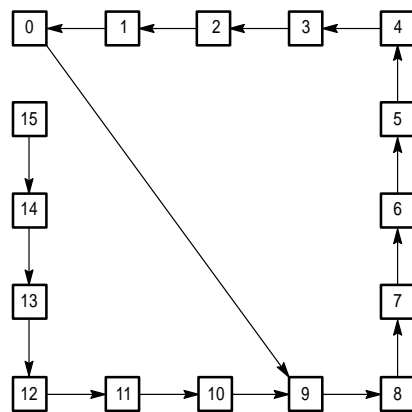
### LOGIC DIAGRAM



STATE DIAGRAM FOR UP COUNTING



STATE DIAGRAM FOR DOWN COUNTING



## PIN DESCRIPTIONS

### INPUTS

**P1, P2, P3, P4, Preset Inputs (Pins 4, 12, 13, 3)** — Data on these inputs is loaded into the counter when PE is taken high.

**Carry In, (Pin 5)** — Active-low input used when cascading stages. Usually connected to Carry Out of the previous stage. While high, clock is inhibited.

**Clock, (Pin 15)** — BCD data is incremented or decremented, depending on the direction of count, on the positive transition of this signal.

### OUTPUTS

**Q1, Q2, Q3, Q4, BCD outputs (Pins 6, 11, 14, 2)** — BCD data is present on these outputs with Q1 corresponding to the least significant bit.

**Carry Out, (Pin 7)** — Used when cascading stages, this pin is usually connected to Carry In of the next stage. This

synchronous output is active low and may also be used to indicate terminal count.

### CONTROLS

**PE, Preset Enable (Pin 1)** — Asynchronously loads data on the Preset Inputs. This pin is active high and will inhibit the clock when high.

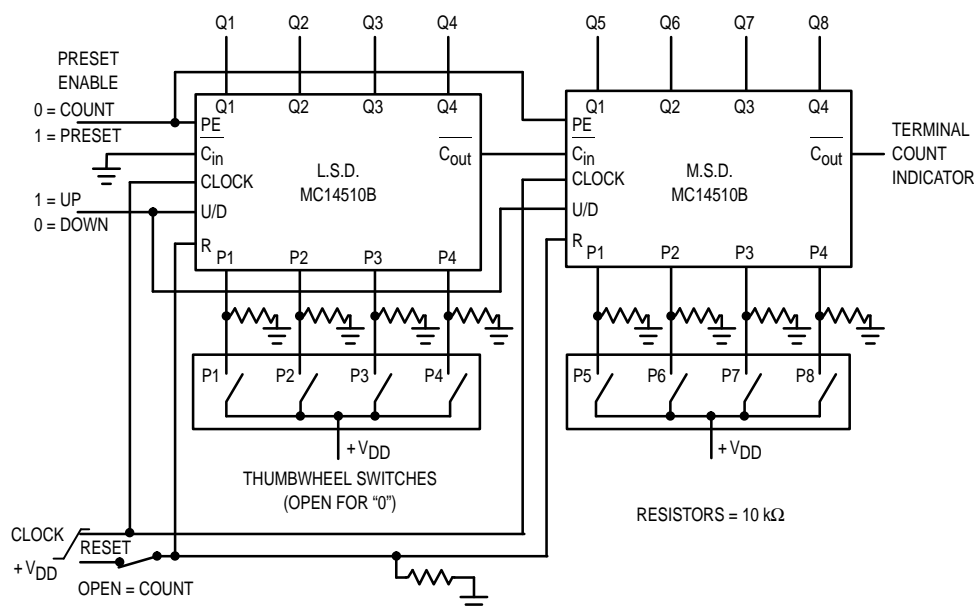
**R, Reset, (Pin 9)** — Asynchronously resets the Q outputs to a low state. This pin is active high and will inhibit the clock when high.

**Up/Down, (Pin 10)** — Controls the direction of count: high for up count, low for down count.

### SUPPLY PINS

**V<sub>SS</sub>, Negative Supply Voltage, (Pin 8)** — This pin is usually connected to ground.

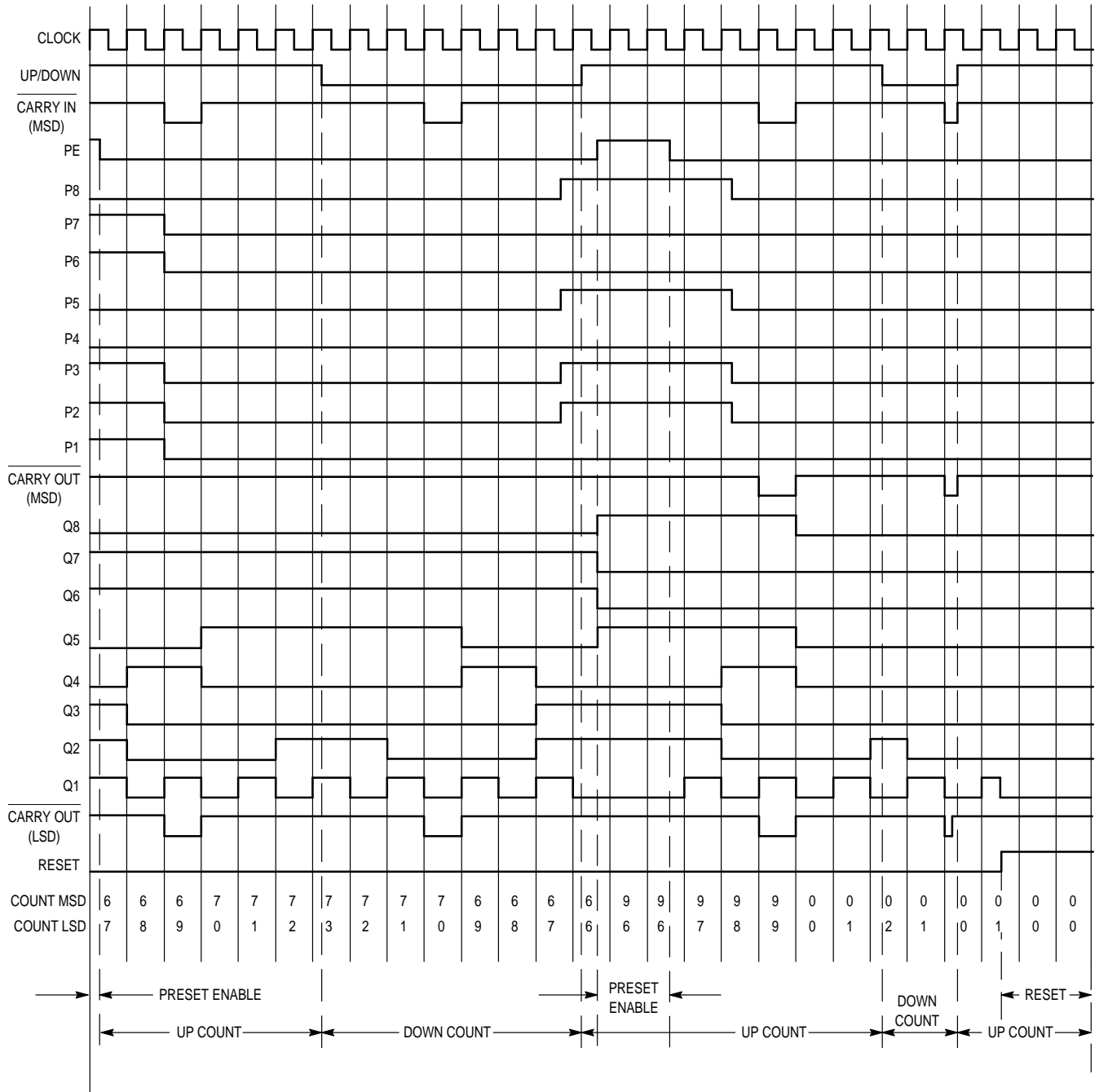
**V<sub>DD</sub>, Positive Supply Voltage, (Pin 16)** — This pin is connected to a positive supply voltage ranging from 3.0 Vdc to 18.0 Vdc.

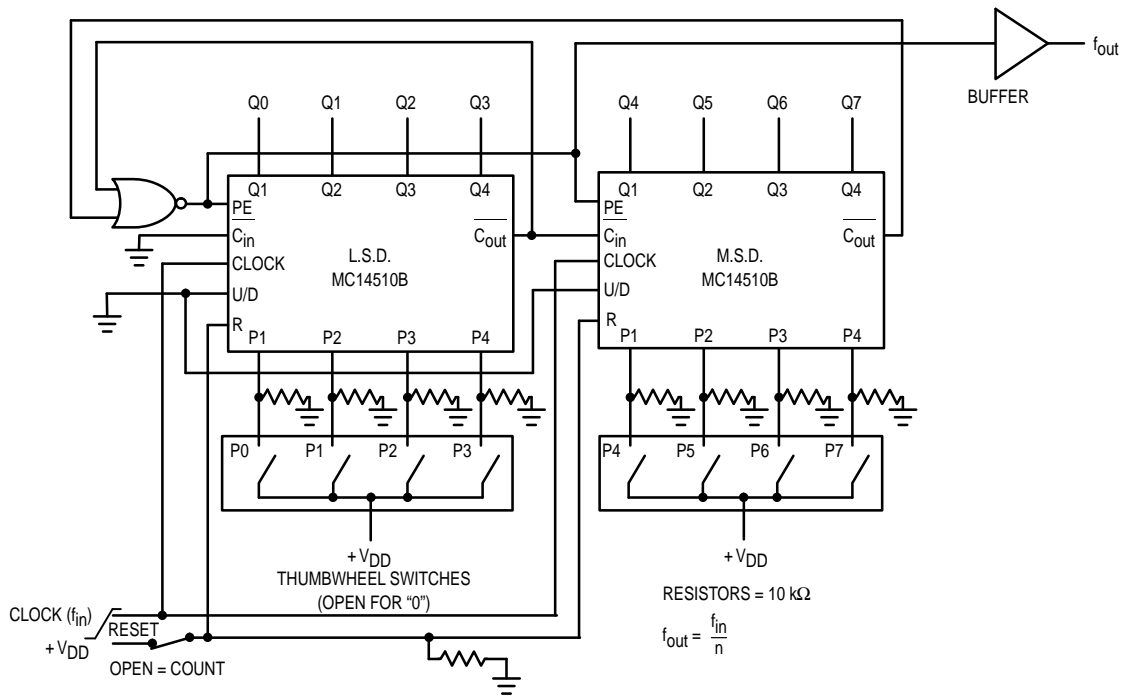


**Note:** The Least Significant Digit (L.S.D.) counts from a preset value once Preset Enable (PE) goes low. The Most Significant Digit (M.S.D.) does not change while  $\overline{C}_{in}$  is high. When the count of the L.S.D. reaches 0 (count down mode) or reaches 9 (count up mode),  $\overline{C}_{out}$  goes low for one complete clock cycle, thus allowing the next counter to decrement/increment one count. The L.S.D. now counts through another cycle (10 clock pulses) and the above cycle is repeated.

Figure 3. Presettable Cascaded 8-Bit Up/Down Counter

**TIMING DIAGRAM FOR THE PRESETTABLE  
CASCADED 8-BIT UP/DOWN COUNTER**





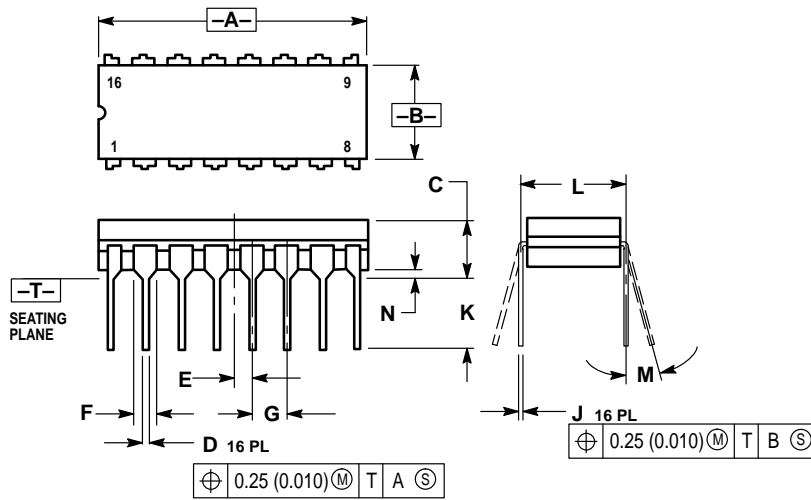
**Note:** The programmable frequency divider can be set by applying the desired divide ratio, in BCD, to the preset inputs. For example, the maximum divide ratio of 99 may be obtained by applying a 10011001 to the preset inputs P0 to P7. For this divide operation, both counters should be configured in the count down mode. The divide ratio of zero is an undefined state and should be avoided.

**Figure 4. Programmable Cascaded Frequency Divider**



## OUTLINE DIMENSIONS

### L SUFFIX CERAMIC DIP PACKAGE CASE 620-10 ISSUE V

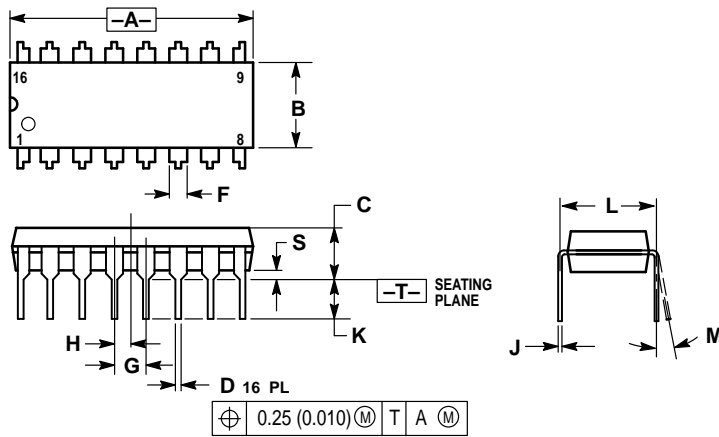


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

### P SUFFIX PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



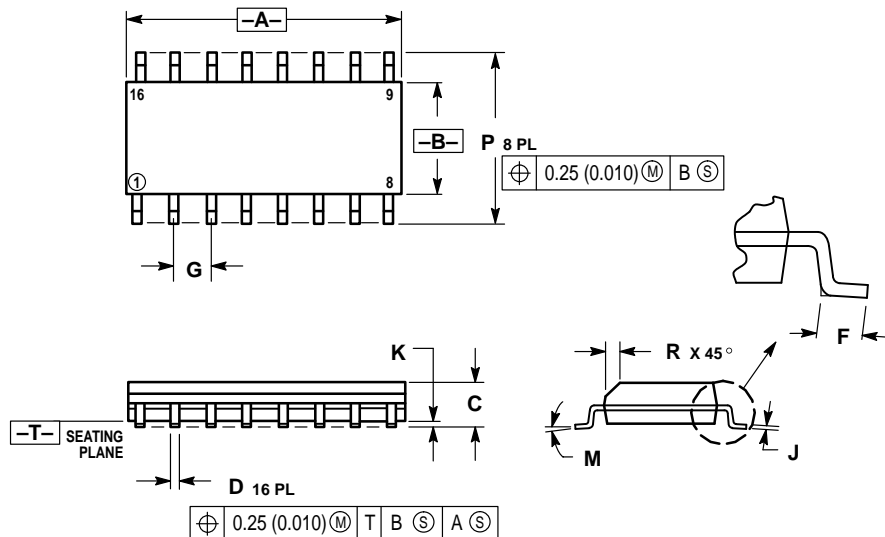
**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

## OUTLINE DIMENSIONS

### D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05 ISSUE J



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

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MC14510B/D



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